

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ho Hyun KIM</td> <td>05/15/2013</td> </tr> <tr> <td>Seung Bae HUR</td> <td>05/15/2013</td> </tr> <tr> <td>Seung Wook SONG</td> <td>05/15/2013</td> </tr> <tr> <td>Jeong Hwan PARK</td> <td>05/15/2013</td> </tr> <tr> <td>Ha Yong YANG</td> <td>05/15/2013</td> </tr> <tr> <td>In Su KIM</td> <td>05/15/2013</td> </tr> </tbody> </table>		Name	Execution Date	Ho Hyun KIM	05/15/2013	Seung Bae HUR	05/15/2013	Seung Wook SONG	05/15/2013	Jeong Hwan PARK	05/15/2013	Ha Yong YANG	05/15/2013	In Su KIM	05/15/2013
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<table border="1"> <tr> <td>Name:</td> <td>MAGNACHIP SEMICONDUCTOR, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728</td> </tr> <tr> <td>City:</td> <td>Cheongju-si</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	MAGNACHIP SEMICONDUCTOR, LTD.	Street Address:	1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728	City:	Cheongju-si	State/Country:	KOREA, REPUBLIC OF						
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13915810</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13915810										
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CORRESPONDENCE DATA															
<p>Fax Number:</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 202-429-0020</p> <p>Email: info@nsiplaw.com</p> <p>Correspondent Name: NSIP LAW</p> <p>Address Line 1: P.O. Box 65745</p> <p>Address Line 4: Washington, DISTRICT OF COLUMBIA 20035</p>															
ATTORNEY DOCKET NUMBER:	023103.0082														
NAME OF SUBMITTER:	Charles Y. Park														
Signature:	/Charles Y. Park/														

OP \$40.00 13915810

Date:	06/12/2013
<b>Total Attachments: 3</b> source=NewApp_0231030082_CDA wAppNumber#page1.tif source=NewApp_0231030082_CDA wAppNumber#page2.tif source=NewApp_0231030082_CDA wAppNumber#page3.tif	

**COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)****DECLARATION**

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto, or to United States Application Number or PCT International Application Number \_\_\_\_\_ filed on \_\_\_\_\_ (if applicable), entitled:

**POWER SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF**

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

**ASSIGNMENT**

For valuable consideration, I, as a below-named assignor, hereby assign to:

Magnachip Semiconductor, Ltd.  
1 Hyangjeong-dong, Heungdeok-gu  
Cheongju-si, Chungcheongbuk-do, 361-728  
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 13/915,810 filed on June 12, 2013.


I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

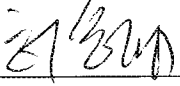
This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-

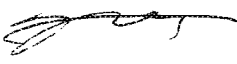
## COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)


identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

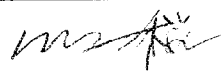
Inventor's Legal Name	Ho Hyun, KIM		
Inventor's Signature		Date	May 15, 2013
Residence (City, Country)	Seoul, Republic of Korea		
Mailing Address	1416-1001, 130, Mokdongdong-ro, Yangcheon-gu, Seoul, 158-774, Republic of Korea		

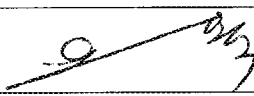
Inventor's Legal Name	Seung Bae, HUR		
Inventor's Signature		Date	May 15, 2013
Residence (City, Country)	Incheon, Republic of Korea		
Mailing Address	708-1202, 27, Cheyukgwang-ro, Bupyeong-gu, Incheon, 403-906, Republic of Korea		

Inventor's Legal Name	Seung Wook, SONG		
Inventor's Signature		Date	May 15, 2013
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Inventor's Legal Name	Jeong Hwan, PARK		
Inventor's Signature		Date	May 15, 2013
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## COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

Inventor's Legal Name	Ha Yong, YANG		
Inventor's Signature		Date	May 15, 2013
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	B-316, Hynix Semiconductor Inc. Men's Dormitory, 959, 2sunhwan-ro, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-719, Republic of Korea		

Inventor's Legal Name	In Su, KIM		
Inventor's Signature		Date	May 15, 2013
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	206-101, 66, Jinjae-ro 9beon-gil, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-815, Republic of Korea		